

# REALTEK

## RTL8723BS-VQ-CG

**SINGLE-CHIP 802.11b/g/n 1T1R WLAN and  
BLUETOOTH 2.1/3.0/4.0 with SDIO INTERFACE, and  
HS-UART MIXED INTERFACE**

### **DATASHEET**

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**USING THIS DOCUMENT**

This document is intended for the software engineer’s reference and provides detailed programming information.

Though every effort has been made to ensure that this document is current and accurate, more information may have become available subsequent to the production of this guide.

**REVISION HISTORY**

Revision	Release Date	Summary
0.3	2013/5/21	Preliminary release.

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## 1. General Description

The Realtek RTL8723BS-VQ-CG is a highly integrated 802.11b/g/n 1T1R WLAN and Bluetooth 2.1/3.0/4.0 single chip. It combines a WLAN MAC, a 1T1R capable WLAN baseband, BT Protocol Stack (LM, LL, and LE), BT Baseband, modem, and WLAN/BT RF in a single chip. The RTL8723BS-VQ-CG provides a complete solution for a high throughput performance integrated wireless LAN, and Bluetooth.

The RTL8723BS-VQ-CG WLAN baseband implements Orthogonal Frequency Division Multiplexing (OFDM) with 1 transmit and 1 receive path and is compatible with the 802.11n specification. Features include one spatial stream transmission, short guard interval (GI) of 400ns, spatial spreading, and transmission over 20MHz and 40MHz bandwidth.

For legacy compatibility, Direct Sequence Spread Spectrum (DSSS), Complementary Code Keying (CCK) and OFDM baseband processing are included to support all 802.11b and 802.11g data rates. Differential phase shift keying modulation schemes, DBPSK and DQPSK with data scrambling capability, are available, and CCK provides support for legacy data rates, with long or short preamble. The high-speed FFT/IFFT paths, combined with BPSK, QPSK, 16QAM, and 64QAM modulation of the individual subcarriers and rate compatible punctured convolutional coding with coding rate of 1/2, 2/3, 3/4, and 5/6, provide higher data rates of 54Mbps and 150Mbps for 802.11g and 802.11n OFDM respectively.

A built-in enhanced signal detector, adaptive frequency domain equalizer, and a soft-decision Viterbi decoder help to alleviate multi-path effects and mutual interference in the reception of multiple streams. Robust interference detection and suppression are provided to protect against Bluetooth, cordless phone, and microwave oven interference.

Efficient IQ-imbalance, DC offset, phase noise, frequency offset, and timing offset compensations are provided for the radio frequency front-end. Selectable digital transmit and receive FIR filters are provided to meet transmit spectrum mask requirements and to reject adjacent channel interference, respectively.

The RTL8723BS-VQ-CG WLAN Controller supports fast receiver Automatic Gain Control (AGC) with synchronous and asynchronous control loops among antennas, antenna diversity functions, and adaptive transmit power control function to obtain better performance in the analog portions of the transceiver.

The RTL8723BS-VQ-CG WLAN MAC supports 802.11e for multimedia applications, 802.11i for security, and 802.11n for enhanced MAC protocol efficiency. Using packet aggregation techniques such as A-MPDU with BA and A-MSDU, protocol efficiency is significantly improved. Power saving mechanisms such as Legacy Power Save, and U-APSD, reduce the power wasted during idle time, and compensate for the extra power required to transmit OFDM. The RTL8723BS-VQ-CG provides simple legacy and 20MHz/40MHz co-existence mechanisms to ensure backward and network compatibility.

RTL8723BS-VQ-CG The RTL8723BS-VQ-CG Bluetooth controller complies with Bluetooth core specification v4.0, and supports dual mode (BR/EDR + AMP + Low Energy Controllers). It is compatible with previous versions, including v2.1 + EDR and v3.0 + HS. For BR/EDR, it supports scatternet topology and allows four active links in slave mode, and seven active links in master mode. For Low Energy, it supports multiple states and allows eight active links in master mode. The links in BR/EDR and LE can be active simultaneously.

## 2. Features

### General

- QFN68 8 x 8 mm
- 802.11b/g/n 1T1R WLAN, and Bluetooth single chip

### Host Interface

- Complies with SDIO 1.1/2.0/3.0 for WLAN with clock rate up to 100MHz (SDR50 and DDR50)
- GSPI interface for configurable endian for WLAN
- Complies with HS-UART with configurable baud rate for Bluetooth

### WLAN Controller

- CMOS MAC, Baseband PHY, and RF in a single chip for 802.11b/g/n compatible WLAN
- Complete 802.11n solution for 2.4GHz band
- 72.2Mbps receive PHY rate and 72.2Mbps transmit PHY rate using 20MHz bandwidth
- 150Mbps receive PHY rate and 150Mbps transmit PHY rate using 40MHz bandwidth
- Compatible with 802.11n specification
- Backward compatible with 802.11b/g devices while operating in 802.11n mode
- 802.11b/g/n compatible WLAN
- 802.11e QoS Enhancement (WMM)
- 802.11i (WPA, WPA2). Open, shared key, and pair-wise key authentication services

### WLAN MAC Features

- Frame aggregation for increased MAC efficiency (A-MSDU, A-MPDU)
- Low latency immediate High-Throughput Block Acknowledgement (HT-BA)
- PHY-level spoofing to enhance legacy compatibility
- Power saving mechanism
- Channel management and co-existence
- Transmit Opportunity (TXOP) Short Inter-Frame Space (SIFS) bursting for higher multimedia bandwidth

### WLAN PHY Features

- 802.11n OFDM
- One Transmit and one Receive path (1T1R)
- 20MHz and 40MHz bandwidth transmission
- Short Guard Interval (400ns)
- DSSS with DBPSK and DQPSK, CCK modulation with long and short preamble
- OFDM with BPSK, QPSK, 16QAM, and 64QAM modulation.  
Convolutional Coding Rate: 1/2, 2/3, 3/4, and 5/6
- Maximum data rate 54Mbps in 802.11g; and 150Mbps in 802.11n
- Switch diversity for DSSS/CCK
- Packet based hardware antenna diversity



- Selectable receiver FIR filters
- Programmable scaling in transmitter and receiver to trade quantization noise against increased probability of clipping
- Fast receiver Automatic Gain Control (AGC)
- On-chip ADC and DAC

### Bluetooth Controller

- Compatible with Bluetooth v2.1+EDR and v3.0+HS Systems
- Supports Bluetooth 4.0 Low Energy(BLE)
- HS-UART interface for Bluetooth data transmission compliant with H4 and H5 specification
- PCM interface for audio data transmission via Bluetooth controller
- Integrated MCU to execute Bluetooth protocol stack
- Supports all packet types in basic rate and enhanced data rate
- Supports SCO/eSCO link (allows one link for PCM interface and three links for HS-UART)
- Supports 4 piconets in a scatternet
- Supports Secure Simple Pairing
- Supports Low Power Mode (Sniff/Sniff Sub-rating/Hold/Park)

- Enhanced BT/WIFI Coexistence Control to improve transmission quality in different profiles
- Bluetooth 4.0 Dual Mode support: Simultaneous LE and BR/EDR
- Supports multiple Low Energy states

### Bluetooth Transceiver

- Fast AGC control to improve receiving dynamic range
- Supports AFH to dynamically detect channel quality to improve transmission quality
- Integrated internal Class 1, Class 2, and Class 3 PA
- Bluetooth 3.0+HS compliant
- Supports Power Control/Enhanced Power Control
- Bluetooth Low Energy Support
- Integrated 32K oscillator for power management

### Peripheral Interfaces

- General Purpose Input/Output (13 pins)
- 4-wire EEPROM control interface (93C46)
- Three configurable LED pins

### 3. Application Diagram

#### 3.1. Integrated Single-Band 11n (1x1) and Bluetooth Controller with Antenna Diversity

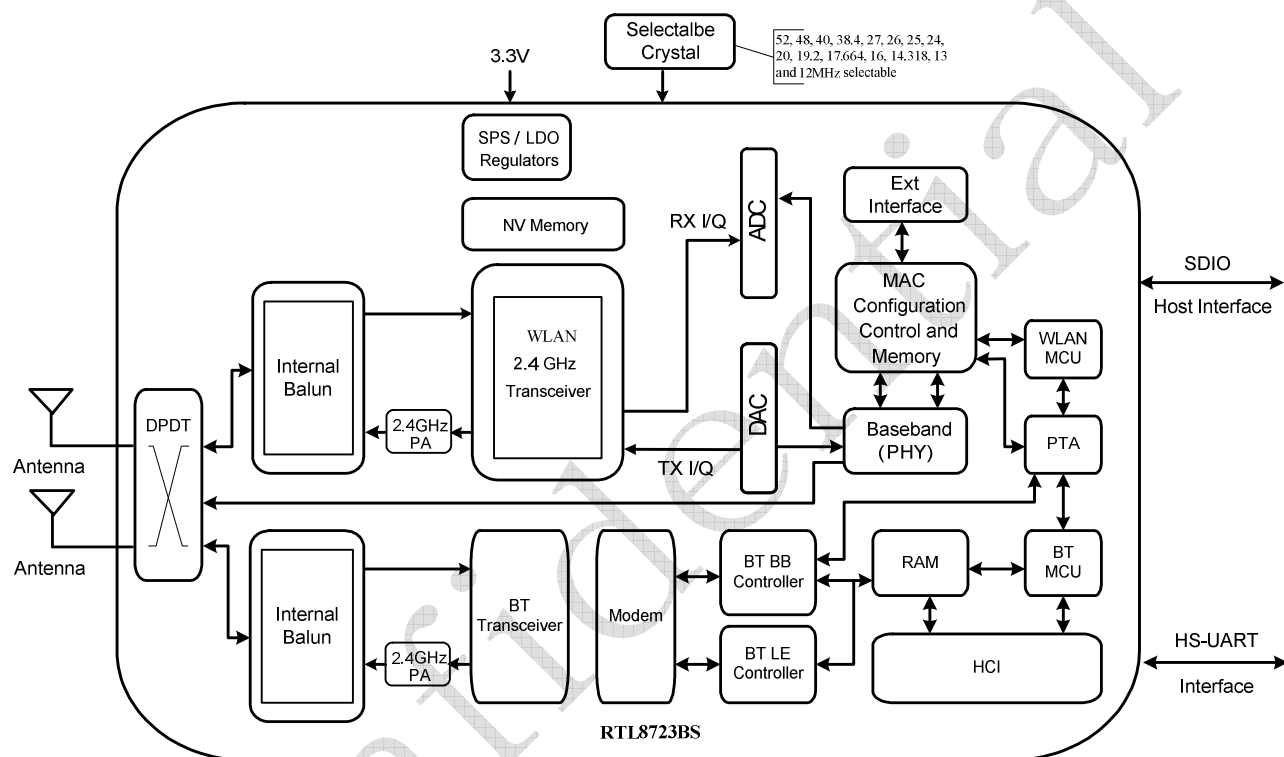


Figure 1. RTL8723BS-VQ-CG with antenna diversity

### 3.2. Integrated Single-Band 11n (1x1) and Bluetooth Controller with WL/BT Shared antenna

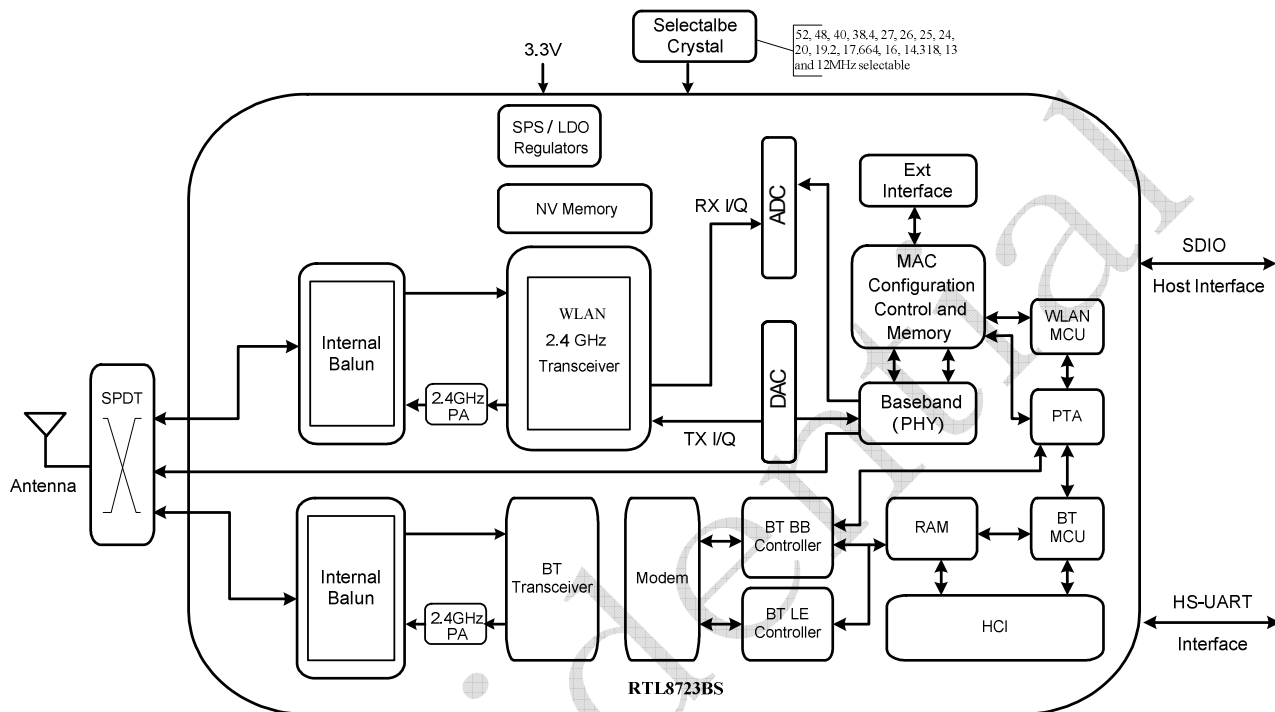


Figure 2. RTL8723BS-VQ-CG with shared antenna between WLAN and Bluetooth

## 4. Pin Assignments

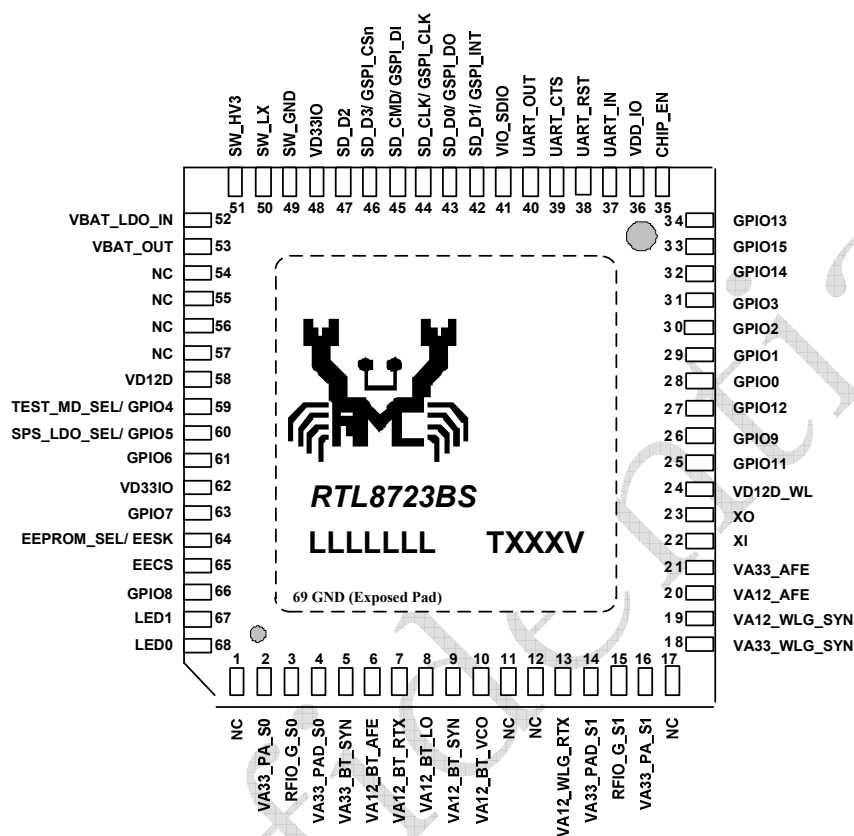


Figure 3. Pin Assignments

## 5. Package Identification

‘Green’ package is indicated by a ‘G’ in the location marked ‘T’ in Figure 3. The version is shown in the location marked ‘V’, e.g., Q=Version Q.

## 6. Pin Descriptions

The following signal type codes are used in the tables:

I: Input

O: Output

## 6.1. Power-On Trap Pins

**Table 1. Power On Trap Pins**

Symbol	Type	Pin No	Description
TEST_MODE_SEL	I	59	Shared with GPIO4 0: Normal operation mode 1: Enter into test/debug mode
SPS_LDO_SEL	I	60	Shared with GPIO5 0: Internal switching regulator select 1: Internal LDO select
EEPROM_SEL	I	64	Shared with EESK pin 0: Internal NV memory select 1: External EEPROM select

## 6.2. SDIO Interface

**Table 2. SDIO Interface**

Symbol	Type	Pin No	Description
SD_CLK	I	44	SDIO Clock Input
SD_CMD	IO	45	SDIO Command Input
SD_D0	IO	43	SDIO Data Line 0
SD_D1	IO	42	SDIO Data Line 1
SD_D2	IO	47	SDIO Data Line 2
SD_D3	IO	46	SDIO Data Line 3

Note: Refer to section 7.5, page 16 for SDIO signal level selection.

## 6.3. GSPI Interface

**Table 3. GSPI Interface**

Symbol	Type	Pin No	Description
GSPI_CLK	I	44	GSPI Clock Input
GSPI_DI	I	45	GSPI Data Input
GSPI_DO	O	43	GSPI Data Out
GSPI_INT	O	42	GSPI Interrupt
GSPI_CSn	I	46	GSPI Chip Select

Note 1: GSPI and SDIO are shared pins.

Note 2: Refer to section 7.5, page 16 for GSPI signal level selection.

## 6.4. HS-UART Transceiver Interface

**Table 4. HS-UART Interface**

Symbol	Type	Pin No	Description
UART_OUT	O	40	High-Speed UART Data Out

Symbol	Type	Pin No	Description
UART_CTS	I	39	High-Speed UART CTS
UART_RTS	O	38	High-Speed UART RTS
UART_IN	I	37	High-Speed UART Data In

Note: Refer to section 7.6.1, page 20 for UART signal level selection.

## 6.5. Log UART Transceiver Interface

**Table 5. Log UART Interface**

Symbol	Type	Pin No	Description
BT_UART_OUT	O	67	Shared with LED1. BT UART Data Out
BT_UART_IN	I	68	Shared with LED0. BT UART Data In
WL_UART_OUT	O	63	Shared with GPIO7. WL UART Data Out
WL_UART_IN	I	61	Shared with GPIO6. WL UART Data In

Note: Refer to section 7.6.1, page 20 for UART signal level selection.

## 6.6. EEPROM Interface

**Table 6. Log UART Interface**

Symbol	Type	Ball No	Description
EECS	O	65	External EEPROM Chip Select
EESK	O	64	External EEPROM Clock
EEDI	I	63	Shared with GPIO7] External EEPROM Data In
EEDO	O	61	Shared with GPIO6. External EEPROM Data Out

Note: Refer to section 7.6.1, page 20 for UART signal level selection.

## 6.7. PCM Interface

**Table 7. PCM Interface**

Symbol	Type	Pin No	Description
PCM_IN	I	28	PCM data Input, shared with GPIO0
PCM_OUT	O	29	PCM data Out, shared with GPIO1
PCM_SYNC	O	30	PCM Synchronization control, shared with GPIO2
PCM_CLK	IO	31	PCM Clock, shared with GPIO3

Note: Refer to section 7.6.1, page 20 for PCM signal level selection.

## 6.8. I<sup>2</sup>S Interface

**Table 8. PCM Interface**

Symbol	Type	Pin No	Description
I2S_IN	I	28	I <sup>2</sup> S Input, shared with GPIO0
I2S_OUT	O	29	I <sup>2</sup> S Out, shared with GPIO1
I2S_WS	O	30	I <sup>2</sup> S Word Synchronization control, shared with GPIO2
I2S_CLK	IO	31	I <sup>2</sup> S Clock, shared with GPIO3

Note: Refer to section 7.6.1, page 20 for PCM signal level selection.

## 6.9. BT 3D Glass Interface

**Table 9. PCM Interface**

Symbol	Type	Pin No	Description
3DG_SYNC_A	I	29	Shared with GPIO1 BT 3D Glass Synchronization control port A.
3DG_SEL_A	I	28	Shared with GPIO0. BT 3D Glass Select control port A.
3DG_SYNC_B	I	61	Shared with GPIO6. BT 3D Glass Synchronization control port B.
3DG_SEL_B	I	65	Shared with EECS. BT 3D Glass Select control port B.

Note: Refer to section 7.6.1, page 20 for PCM signal level selection.

## 6.10. RF Interface

**Table 10. RF Interface**

Symbol	Type	Pin No	Description
RFIO_G_S0	IO	3	WLAN/BT RF TX/RX signal port 0
RFIO_G_S1	IO	15	WLAN/BT RF TX/RX signal port 1
DPDT_SEL_P	O	64	Shared with EESK. Antenna Select control Positive signal
DPDT_SEL_N	O	65	Shared with EECS. Antenna Select control Negative signal

## 6.11. LED Interface

**Table 11. LED Interface**

Symbol	Type	Pin No	Description
LED0	O	68	LED Pin (Active Low)
LED1	O	67	LED Pin (Active Low)
LED2	O	66	LED Pin (Active Low), shared with GPIO8

## 6.12. Power Management Handshake Interface

**Table 12. Power Management Handshake Interface**

Symbol	Type	Pin No	Description
CHIP_EN	I	35	This Pin Can externally shut down the RTL8723BS-VQ-CG (No Extra Power Switch Required). When this function is not required, external pull high is required.
WL_DISn	I	26	Shared with GPIO9 This Pin Can Externally Shutdown the RTL8723BS-VQ-CG WLAN function when WL_DISn is Pulled Low. When this pin deasserted, SDIO interface will be disabled. This pin can also support the WLAN Radio-off function with host interface remaining connected.
BT_DISn	I	25	Shared with GPIO11. This Pin Can Externally Shutdown the RTL8723BS-VQ-CG BT function when BT_DISn is Pulled Low. This pin can also support the BT Radio-off function with host interface remaining connected.
DEV_WAKE_HOST	O	32	Shared with GPIO4 This pin is shared with both WIFI and BT functions to wakeup the host when the remote wake function is enabled. The Polarity can be defined by the customer.
HOST_WAKE_DEV	I	34	Shared with GPIO13 The Host wakes up the WLAN and Bluetooth controller in Remote Wakeup Mode.
CLKREQ	O	33	Shared with GPIO15. When RTL8723B XTAL clock is fed from host chipset, it will assert CLKREQ to request XTAL clock. Otherwise, RTL8723BS-VQ-CG will de-assert CLKREQ to indicate host chipset that there is no need to output the XTAL clock to RTL8723BS-VQ-CG. This signal is used for power saving control with host chipset.

## 6.13. Clock and Other Pins

**Table 13. Clock and Other Pins**

Symbol	Type	Pin No	Description
XI	I	22	26M/40MHz OSC Input Input of 26M/40MHz Crystal Clock Reference
XO	O	23	Output of 26MHz/40MHz Crystal Clock Reference
SUS_CLK	I	61	Shared with GPIO6. External 32K or RTC clock input.
GPIO0	IO	28	General Purpose Input/Output Pin
GPIO1	IO	29	General Purpose Input/Output Pin
GPIO2	IO	30	General Purpose Input/Output Pin
GPIO3	IO	31	General Purpose Input/Output Pin
GPIO4	IO	59	General Purpose Input/Output Pin
GPIO5	IO	60	General Purpose Input/Output Pin
GPIO6	IO	61	General Purpose Input/Output Pin
GPIO7	IO	63	General Purpose Input/Output Pin
GPIO8	IO	66	General Purpose Input/Output Pin



Symbol	Type	Pin No	Description
GPIO9	IO	26	General Purpose Input/Output Pin
GPIO11	IO	25	General Purpose Input/Output Pin
GPIO12	IO	27	General Purpose Input/Output Pin

## 6.14. Power Pins

**Table 14. Power Pins**

Symbol	Type	Pin No	Description
VBAT_LDO_IN	P	52	Battery LDO input, 5.5V ~ 2.8V
VBAT_LDO	P	53	Battery LDO output, 3.3V
SW_LX	P	50	Switching Regulator Output
SW_HV3	P	51	Switching Regulator Input Or Linear Regulator input from 3.3V to 1.5V
VA33_PA_S0, VA33_PAD_S0, VA33_BT_SYN, VA33_PAD_S1, VA33_PA_S1, VA33_WLG_SYN, VA33_AFE	P	2, 4, 5 14, 16, 18, 21,	3.3V for Analog Circuit
VD33IO	P	48, 62	VDD3.3V for Digital IO
VIO_SDIO	P	41	VDD for SDIO and UART Pin, the power supply is same as the signal level of SDIO bus and UART bus (3.3V~1.8V)
VDD_IO	P	36	VDD for GPIO0 to GPIO3 and GPI[9]to GPIO12 (3.3V~1.8V)
VD12D	P	24, 58	VDD 1.2V Digital Circuit
VA12	P	19, 20	1.2V for analog blocks
VA12_BT_AFE, VA12_BT_RTX, VA12_BT_LO, VA12_BT_SYN, VA12_BT_VCO	P	6, 7, 8, 9, 10	1.2V for BT analog circuit
VA12_WLG_RTX, VA12_WLG_SYN, VA12_AFE	P	13, 19, 20	1.2V for WL analog circuit
SW_GND	P	49	Switching Regulator Ground

## 6.15. Not Connected Pins

**Table 15. Not Connected Pins**

Symbol	Type	PinNo	Description
NC	-	1 11, 12, 17, 54, 55, 56, 57	Not Connected Pins

## 7. Electrical and Thermal Characteristics

### 7.1. Temperature Limit Ratings

**Table 16. Temperature Limit Ratings**

Parameter	Minimum	Maximum	Units
Storage Temperature	-55	+125	°C
Ambient Operating Temperature	0	70	°C
Junction Temperature	0	125	°C

### 7.2. Power Supply DC Characteristics

**Table 17. Power Supply DC Characteristics**

Symbol	Parameter	Minimum	Typical	Maximum	Units
VBAT_LDO_IN	Battery Supply Voltage	2.8	3.7~5	5.5	V
VA33, VD33IO, SW_HV3,	3.3V Supply Voltage	3.0	3.3	3.6	V
VDD_IO, VDIO_SDIO	Digital IO Supply Voltage	1.62	1.8~3.3	3.6	V
VA12, VA12_BT, VA12_WLG, VD12D	1.2V Core Supply Voltage	1.08	1.2	1.32	V
IDD33	3.3V Rating Current	-	-	600	mA

### 7.3. Digital IO Pin DC Characteristics

**Table 18. 3.3V IO DC Characteristics**

Symbol	Parameter	Minimum	Normal	Maximum	Units
V <sub>IH</sub>	Input high voltage	2.0	3.3	3.6	V
V <sub>IL</sub>	Input low voltage	-	0	0.9	V
V <sub>OH</sub>	Output high voltage	2.97	-	3.3	V
V <sub>OL</sub>	Output low voltage	0	-	0.33	V

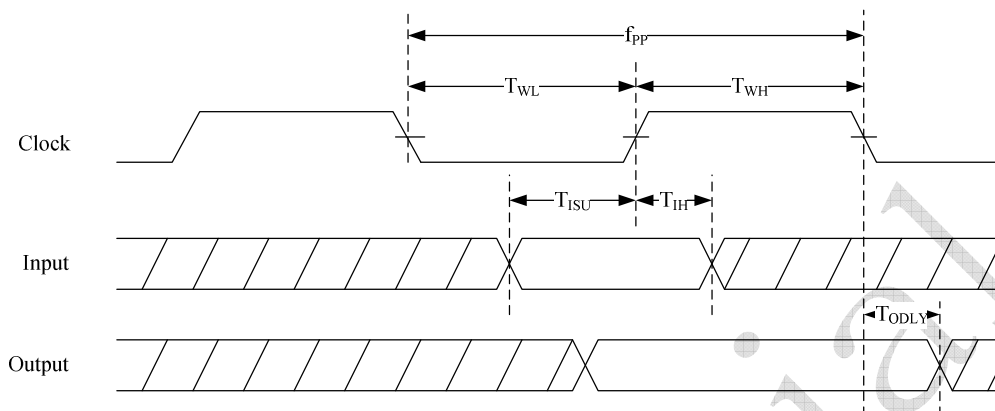
**Table 19. 2.8V IO DC Characteristics**

Symbol	Parameter	Minimum	Normal	Maximum	Units
V <sub>IH</sub>	Input high voltage	1.8	2.8	3.1	V
V <sub>IL</sub>	Input low voltage	-	0	0.8	V
V <sub>OH</sub>	Output high voltage	2.5	-	3.1	V
V <sub>OL</sub>	Output low voltage	0	-	0.28	V

**Table 20. 1.8V IO DC Characteristics**

Symbol	Parameter	Minimum	Normal	Maximum	Units
V <sub>IH</sub>	Input high voltage	1.7	1.8	2.0	V
V <sub>IL</sub>	Input low voltage	-	0	0.8	V
V <sub>OH</sub>	Output high voltage	1.62	-	1.8	V
V <sub>OL</sub>	Output low voltage	0	-	0.18	V

## 7.4. SDIO/GSPI Interface AC Characteristics



**Figure 4. SDIO Interface Timing**

**Table 21. SDIO Interface Timing Parameters**

NO	Parameter	Mode	MIN	MAX	Unit
$f_{PP}$	Clock Frequency	Default	0	25	MHz
		HS	0	50	MHz
$T_{WL}$	Clock Low Time	DEF	10	-	ns
		HS	7	-	ns
$T_{WH}$	Clock High Time	DEF	10	-	ns
		HS	7	-	ns
$T_{ISU}$	Input Setup Time	DEF	5	-	ns
		HS	6	-	ns
$T_{IH}$	Input Hold Time	DEF	5	-	ns
		HS	2	-	ns
$T_{ODLY}$	Output Delay Time	DEF	-	14	ns
		HS	-	14	ns

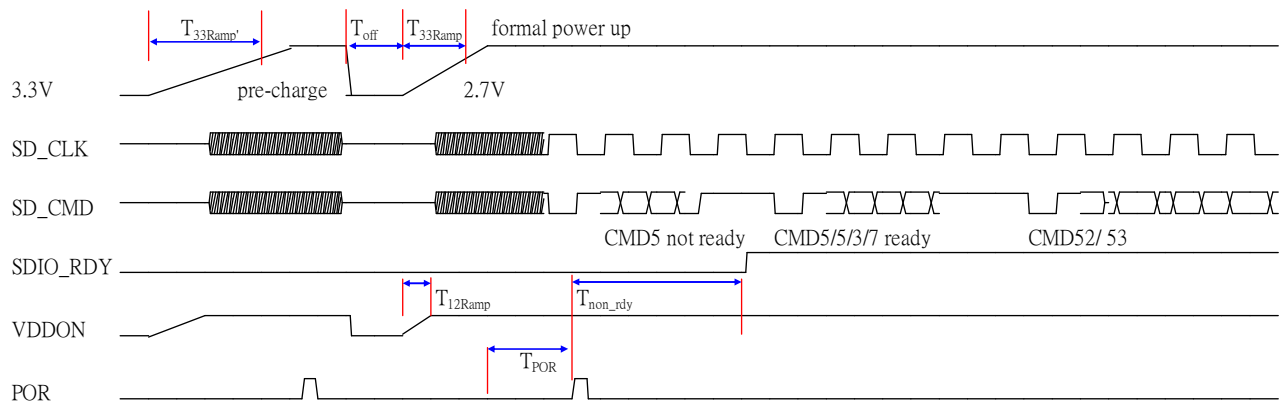
## 7.5. SDIO/GSPI Interface Signal Levels

The SDIO and GSPI signal level ranges from 1.8V to 3.3V. The host provides the power source with the target power level to the RTL8723BS-VQ-CG SDIO and GSPI interfaces via the VDIO\_SDIO pin (Ball H101).

The 3.3V, 2.8V, and 1.8V DC characteristics of typical signal levels are shown in section 7.3 Digital IO Pin DC Characteristics, page 14.

### 7.5.1. SDIO Interface Power-On Sequence

After power-on, the SDIO interface is selected by the RTL8723BS-VQ-CG automatically when a valid SDIO command is received. To attain better SDIO host compatibility, the following power-on sequence is recommended.



**Figure 5. SDIO Interface Power-On Sequence**

**Table 22. SDIO Interface Power-On Sequence**

Symbol	Description
$T_{33ramp}$	3.3V Power Pre-Charge Ramp Up Duration Before Formal Power Up. We recommend that a 3.3V power-on and then power-off sequence is executed by the host controller before the formal power on sequence. This procedure can eliminate host card detection issues when power ramp up duration is too long, or when a system warm reboot fails.
$T_{off}$	The duration 3.3V is cut off before formal power up.
$T_{33ramp}$	The 3.3V main power ramp up duration.
$T_{12ramp}$	The internal 1.2V ramp up duration.
$T_{POR}$	The duration from when the power-on reset releases and the power management unit executes power on tasks. A power on reset will detect both 3.3V and 1.2V power ramp up after a predetermined duration.
$T_{non\_rdy}$	SDIO Not Ready Duration. In this state, the RTL8723BS-VQ-CG may respond to commands without the ready bit being set. After the ready bit is set, the host will initiate complete card detection procedure.

We recommend that the card detection procedures are divided into two phases: A 3.3V power pre-charge phase and a formal power-up phase.

During the 3.3V power pre-charge phase, the power ramp up duration is not limited. The 3.3V power is cut off and is turned on after the  $T_{off}$  period. The ramp up time is specified in the  $T_{33ramp}$  duration.

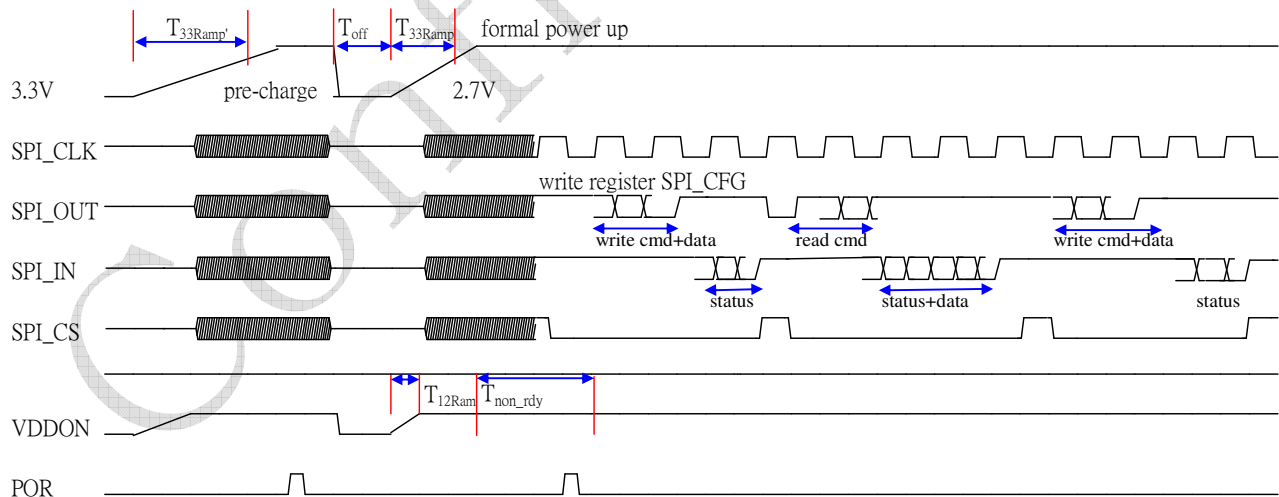
After main 3.3V ramp up and 1.2V ramp up, the power management unit is enabled by the power ready detection circuit. The power management unit enables the SDIO block. eFUSE is then autoloading to SDIO circuits during the  $T_{non\_rdy}$  duration. After the autoload has completed, the SDIO sets the ready bit. After CMD5/5/3/7 procedures, card detection is executed. When the driver has loaded, normal CMD52 and CMD53 are used.

**Table 23. SDIO Interface Power-On Timing Parameters**

Symbol	Min	Typical	Max	Unit
$T_{33ramp}$	-	-	No Limit	ms
$T_{off}$	250	500	1000	ms
$T_{33ramp}$	0.1	0.5	2.5	ms
$T_{12ramp}$	0.1	0.5	1.5	ms
$T_{POR}$	2	2	8	ms
$T_{non\_rdy}$	1	2	10	ms

### 7.5.2. GSPI Interface Power-On Sequence

The GSPI (Generic Serial Peripheral Interface) interface is enabled automatically when the first valid GSPI command is received.



**Figure 6. GSPI Interface Power-On Sequence**

**Table 24. GSPI Interface Power-On Sequence**

Symbol	Description
$T_{33\text{ramp}}$	3.3V Power Pre-Charge Ramp Up Duration Before Formal Power Up. We recommend that a 3.3V power-on and then power-off sequence is executed by the host controller before the formal power on sequence. This procedure can eliminate host card detection issues when power ramp up duration is too long, or when a system warm reboot fails.
$T_{\text{off}}$	The duration 3.3V is cut off before formal power up.
$T_{33\text{ramp}}$	The 3.3V main power ramp up duration.
$T_{12\text{ramp}}$	The internal 1.2V ramp up duration.
$T_{\text{non\_rdy}}$	SPI Not Ready Duration. After $T_{\text{non\_rdy}}$ , SPI host can then send command to write SPI_CFG register. SPI_CFG register is to control SPI endian and word length.

We recommend that the card detection procedures are divided into two phases: A 3.3V power pre-charge phase and a formal power-up phase.

During the 3.3V power pre-charge phase, the power ramp up duration is not limited. The 3.3V power is cut off and is turned on after the  $T_{\text{off}}$  period. The ramp up time is specified in the  $T_{33\text{ramp}}$  duration.

After main 3.3V ramp up and 1.2V ramp up, the power management unit is enabled by the power ready detection circuit. The power management unit enables the SPI block. eFUSE is then autoloading to SPI circuits during the  $T_{\text{non\_rdy}}$  duration.

**Table 25. SPI Interface Power-On Timing Parameters**

	Min	Typical	Max	Unit
$T_{33\text{ramp}}$	-	-	No Limit	ms
$T_{\text{off}}$	250	500	1000	ms
$T_{33\text{ramp}}$	0.1	0.5	2.5	ms
$T_{12\text{ramp}}$	0.1	0.5	1.5	ms
$T_{\text{non\_rdy}}$	3	4	18	ms

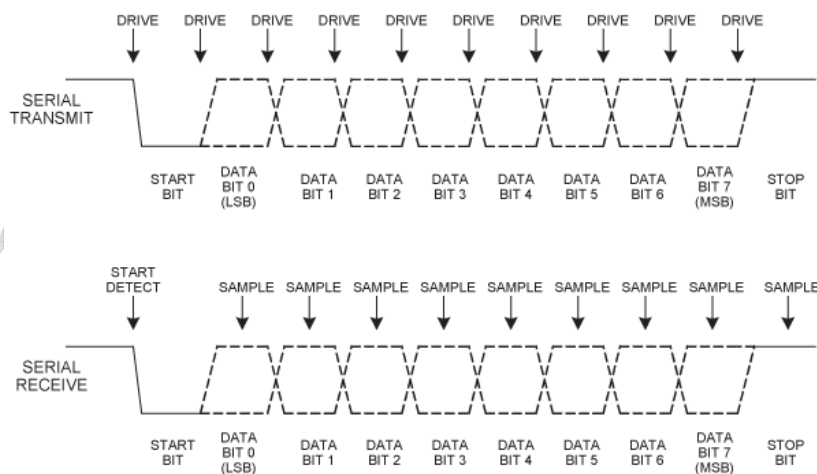
## 7.6. UART Interface Characteristics

The RTL8723BS-VQ-CG UART interface is a standard 4-wire interface with RX, TX, CTS, and RTS. The interface supports the Bluetooth 2.0 UART HCI H4 and H5 specifications. The default baud rate is 115.2k baud. In order to support high and low speed baud rate, the RTL8723BS-VQ-CG provides multiple UART clocks.

**Table 26. UART Interface Power-On Timing Parameters**

Desired Baud Rate	Actual Baud Rate	Error (%)
300	300	0.00%
600	600	0.00%
900	900	0.00%
1200	1200	0.00%
1800	1800	0.00%
2400	2400	0.00%
3600	3601	0.03%
4800	4798	-0.04%
7200	7198	-0.03%
9600	9603	0.03%
14400	14395	-0.03%
19200	19182	-0.09%
28800	28846	0.16%
38400	38462	0.16%
56000	55970	-0.05%
57600	57692	0.16%
76800	76531	-0.35%
115200	115385	0.16%
128000	127119	-0.69%

Desired Baud Rate	Actual Baud Rate	Error (%)
153600	153061	-0.35%
230400	229167	-0.54%
460800	458333	-0.54%
500000	500000	0.00%
921600	916667	-0.54%
1000000	1000000	0.00%
1382400	1375000	-0.54%
1444444	1437500	-0.48%
1500000	1500000	0.00%
1843200	1833333	-0.54%
2000000	2000000	0.00%
2100000	2083333	-0.79%
2764800	2777778	0.47%
3000000	3000000	0.00%
3250000	3250000	0.00%
3692300	3703704	0.31%
3750000	3750000	0.00%
4000000	4000000	0.00%





**Figure 7. UART Interface Waveform**

### 7.6.1. UART Interface Signal Levels

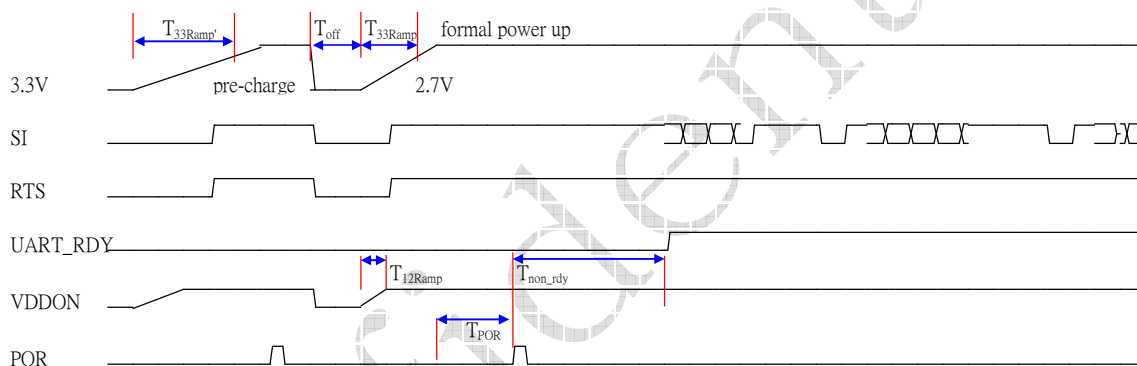
The UART signal level ranges from 1.8V to 3.3V. The host provides the power source with the targeted power level to the RTL8723BS-VQ-CG UART interface via the VDIO\_SDIO pin (5Ball H10).

The 3.3V, 2.8V, and 1.8V DC characteristics of typical signal levels are shown in section 7.3 Digital IO Pin DC Characteristics, page 14.

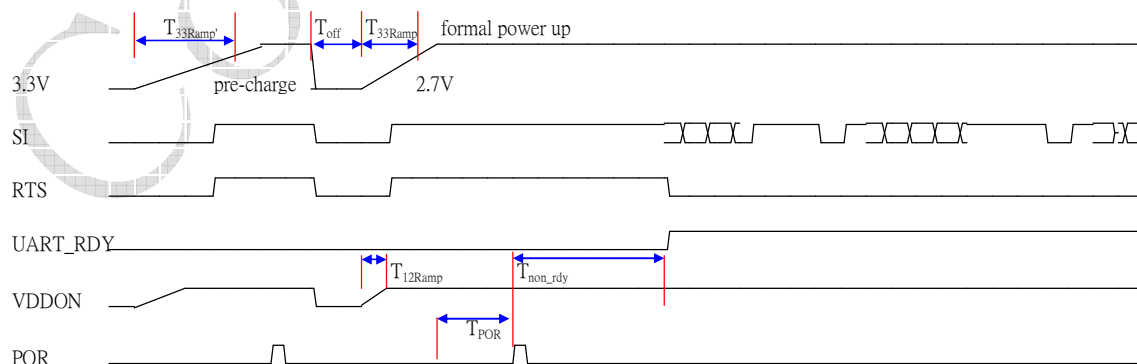
### 7.6.2. UART Interface Power-On Sequence

The UART interface power-on sequence differs depending on whether or not host flow control is supported.

#### UART Hardware Flow Control Not Supported


**Figure 8. UART Power-On Sequence Without Hardware Flow Control**

#### UART Hardware Flow Control Supported



**Figure 9. UART Power On Sequence With Hardware Flow Control**
**Table 27. UART Interface Power-On Sequence**

Symbol	Description
$T_{33ramp}$	3.3V Power Pre-Charge Ramp Up Duration Before Formal Power Up. We recommend that a 3.3V power-on and then power-off sequence is executed by the host controller before the formal power on sequence. This procedure can eliminate host card detection issues when power ramp up duration is too long, or when a system warm reboot fails.
$T_{off}$	The duration 3.3V is cut off before formal power up.
$T_{33ramp}$	The 3.3V main power ramp up duration.
$T_{12ramp}$	The internal 1.2V ramp up duration.
$T_{POR}$	The duration from when the power-on reset releases and the power management unit executes power on tasks. A power on reset will detect both 3.3V and 1.2V power ramp up after a predetermined duration.
$T_{non\_rdy}$	UART Not Ready Duration. In this state, the RTL8723BS-VQ-CG will not respond to any commands.

We recommend that the card detection procedures are divided into two phases: A 3.3V power pre-charge phase and a formal power-up phase.

During the 3.3V power pre-charge phase, the power ramp up duration is not limited. The 3.3V power is cut off and is turned on after the  $T_{off}$  period. The ramp up time is specified in the  $T_{33ramp}$  duration.

After main 3.3V ramp up and 1.2V ramp up, the power management unit is enabled by the power ready detection circuit. The power management unit enables the Bluetooth block. The Bluetooth firmware then initializes all circuits, included the UART. In addition to wait the  $T_{non\_rdy}$  time, if the host supports UART hardware flow control it can detect RTS signals and follow the formal UART flow control handshake.

**Table 28. UART Interface Power On Timing Parameters**

	Min	Typical	Max	Unit
$T_{33ramp}$	-	-	No Limit	ms
$T_{off}$	250	500	1000	ms
$T_{33ramp}$	0.1	0.5	2.5	ms
$T_{12ramp}$	0.1	0.5	1.5	ms
$T_{por}$	2	2	8	ms
$T_{non\_rdy}$	1	2	10	ms

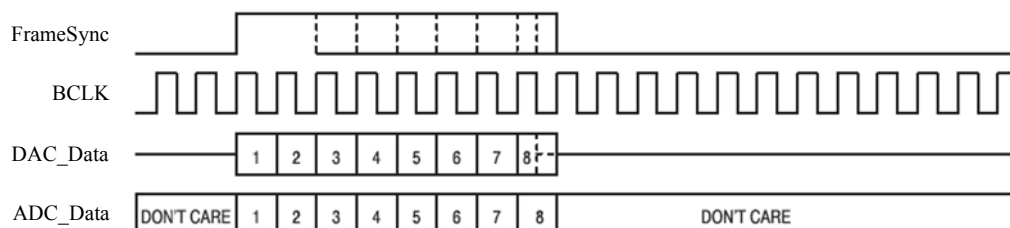
## 7.7. PCM Interface Characteristics

The RTL8723 supports a PCM digital audio interface that is used for transmitting digital audio/voice data to/from the Audio Codec. Features are supported as below:

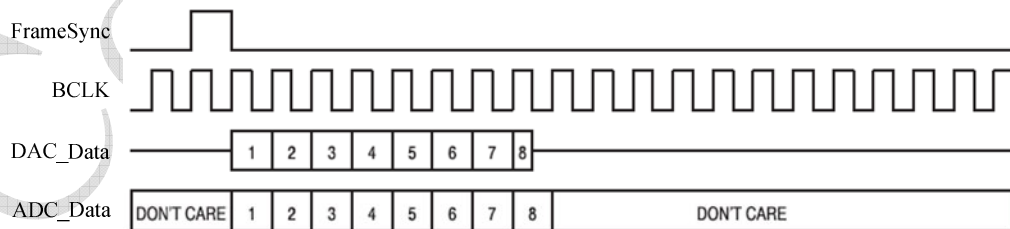
- Supports Master and Slave mode
- Programmable long/short Frame Sync
- Supports 8-bit A-law/ $\mu$ -law, and 13/16-bit linear PCM formats
- Supports sign-extension and zero-padding for 8-bit and 13-bit samples
- Supports padding of Audio Gain to 13-bit samples
- PCM Master Clock Output: 64, 128, 256, or 512kHz
- Supports SCO/ESCO link

### 7.7.1. PCM Format

FrameSync is the synchronizing function used to control the transfer of DAC\_Data and ADC\_Data. A Long FrameSync indicates the start of ADC\_Data at the rising edge of FrameSync (Figure 10), and a Short FrameSync indicates the start of ADC\_Data at the falling edge of FrameSync (Figure 11).



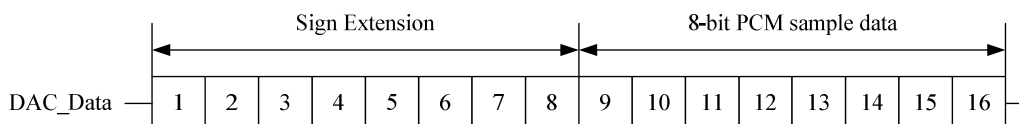
**Figure 10. Long FrameSync**



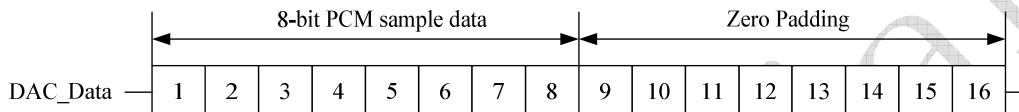
**Figure 11. Short FrameSync**

### 7.7.2. Sign Extension and Zero Padding for 8-Bit and 13-Bit Samples

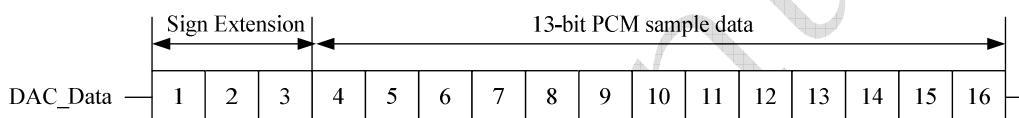
For 16-bit linear PCM output, 3 or 8 unused bits may be sign extended/zero padded.



**Figure 12. 16-Bit Output Data with 8-Bit PCM Sample Data and Sign Extension**

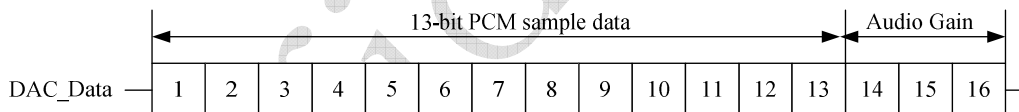


**Figure 13. 16-Bit Output Data with 8-Bit PCM Sample Data and Zero Padding**



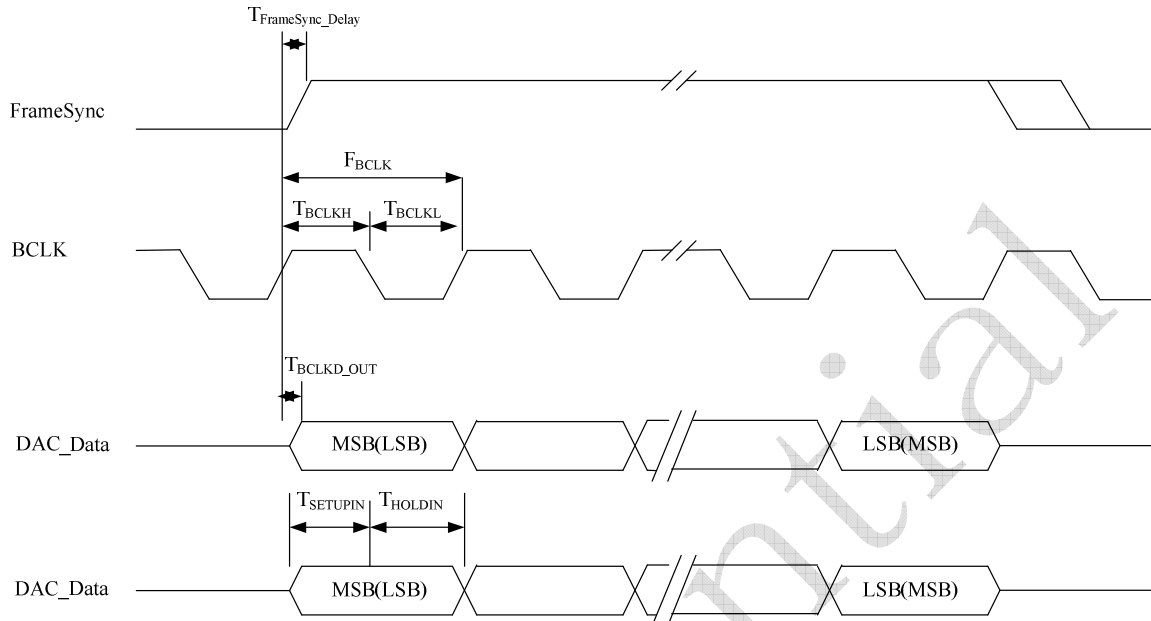
**Figure 14. 16-Bit Output Data with 13-Bit PCM Sample Data and Sign Extension**

For 16-bit linear PCM output, 3-bit programmable audio gain value can be padded to 13-bit sample data.

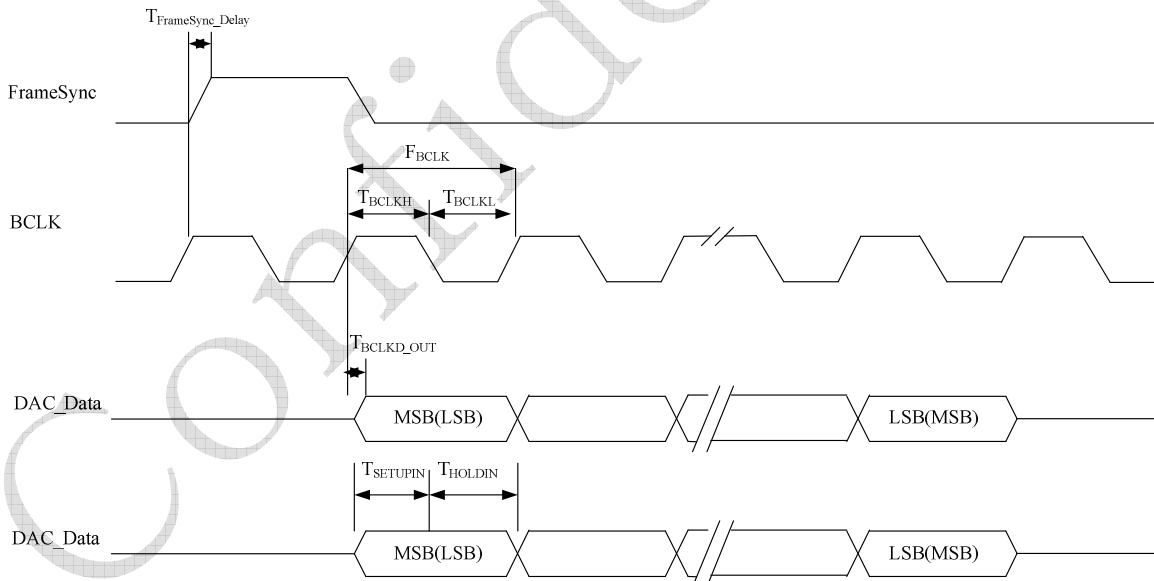


**Figure 15. 16-Bit Output Data with 13-Bit PCM Sample Data and Audio Gain**

### 7.7.3. PCM Interface Timing



**Figure 16. PCM Interface (Long FrameSync)**



**Figure 17. PCM Interface (Short FrameSync)**

**Table 29. PCM Interface Clock Specifications**

Symbol	Description	Min.	Typ.	Max.	Unit
F <sub>BCLK</sub>	Frequency of BCLK (Master)	64	-	512	kHz
F <sub>FrameSync</sub>	Frequency of Frame Sync (Master)	-	8	-	kHz
F <sub>BCLK</sub>	Frequency of BCLK (Slave)	64	-	512	kHz
F <sub>FrameSync</sub>	Frequency of Frame Sync (Slave)	-	8	-	kHz
D	Data Size	8	8	16	bits
N	Number of Slots Per Frame	1	1	1	Slots

**Table 30. PCM Interface Timing**

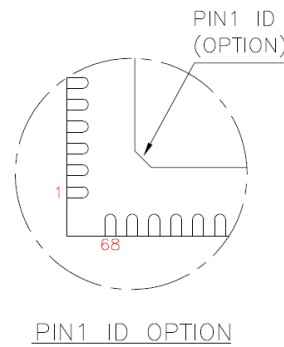
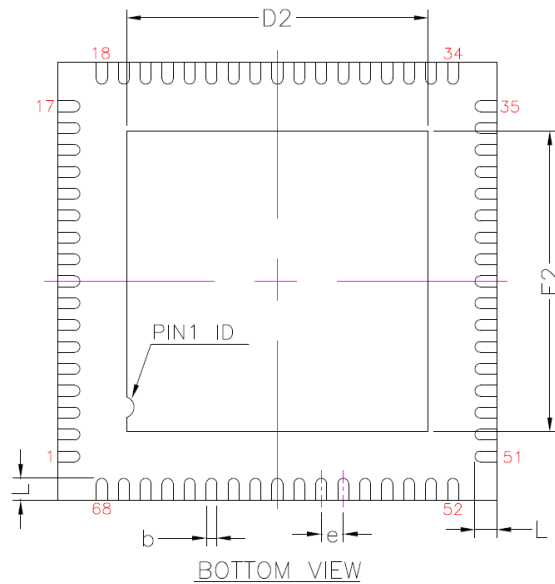
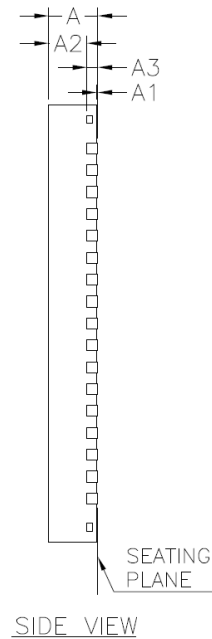
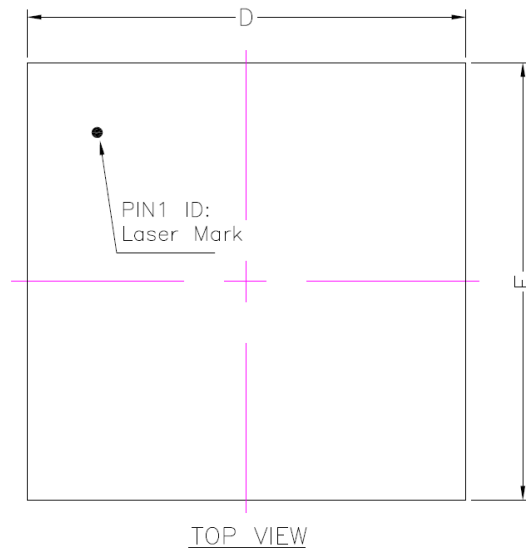
Symbol	Description	Min.	Typ.	Max.	Unit
T <sub>BCLKH</sub>	High Period of BCLK	980	-	-	ns
T <sub>BCLKL</sub>	Low Period of BCLK	970	-	-	ns
T <sub>FrameSync_Delay</sub>	Delay Time from BCLK High to Frame Sync High	-	-	75	ns
T <sub>BCLKD_OUT</sub>	Delay Time from BCLK High to Valid DAC_Data	-	-	125	ns
T <sub>SETUPIN</sub>	Set-up Time for ADC_Data Valid to BCLK Low	10	-	-	ns
T <sub>HOLDIN</sub>	Hold Time for BCLK Low to ADC_Data Invalid	125	-	-	ns

#### 7.7.4. PCM Interface Signal Levels

The PCM signal level ranges from 1.8V to 3.3V. The host provides the power source with the targeted power level to the RTL8723BS-VQ-CG PCM interface via the VDD\_IO pin (Ball J105).

The 3.3V, 2.8V, and 1.8V DC characteristics of typical signal levels are shown in section 7.3 Digital IO Pin DC Characteristics, page 14.

## 8. Mechanical Dimensions



## 8.1. Mechanical Dimensions Notes

Symbol	Dimension in mm			Dimension in inch		
	Min	Nom	Max	Min	Nom	Max
A	0.80	0.85	0.90	0.031	0.033	0.035
A <sub>1</sub>	0.00	0.02	0.05	0.000	0.001	0.002
A <sub>2</sub>	---	0.65	0.70	---	0.026	0.028
A <sub>3</sub>	0.19	0.2 REF	0.21	0.0075	0.008 REF	0.0083
b	0.15	0.20	0.25	0.006	0.008	0.010
D/E	7.95	8.00 BSC	8.05	0.313	0.315 BSC	0.317
D <sub>2</sub> /E <sub>2</sub>	5.25	5.50	5.75	0.207	0.217	0.227
e	0.35	0.40 BSC	0.45	0.0138	0.016 BSC	0.0177
L	0.30	0.40	0.50	0.012	0.016	0.020

Note1: CONTROLLING DIMENSION : MILLIMETER(mm)

Note2: REFERENCE DOCUMENTL : JEDEC MO-220



## 9. Ordering Information

**Table 31. Ordering Information**

Part Number	Package	Status
RTL8723BS-VQ-CG	QFN-68, 'Green' Package	Engineering Samples

*Note: See page 7 for package identification.*

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